目录

电性参数

典型特性曲线

可靠性实验

外形尺寸

包装

焊接指导

使用注意事项

电性参数

Power Dissipation	Pd	125	mw
(Continuous Forward Current)	IF	50	mA
Pulsed Forward Current (1/10Duty Cycle, 0.1msPulsewidth	IFP	200	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	
Storage Temperature	Tstg	-40 ~ +85	
(Junction Temperature)	Tj	Ò115	

光电参数 Ta=25

utions (1)

贮存：

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

30 60%RH

Before opening the package, the product should be kept at 30 or less and humidity less than 60% RH, and be used within a year.

30 10%RH 168 7

30 60%RH

After opening the package, the product should be stored at 30 or less and humidity less than 10%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30 or less and humidity less than 60%RH.

If the moisture absorbent mat

使用注意事项（2）

Precautions (2)

LE

A

LED

In designing a circuit, t ed

for each LED. In the mea ill

cause big current change,

It is recommended to

When handling the product, touching the encapsulant with hands will not only contaminate its surface, but also affect